



Device Material Content

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Assembly: ASEK
Size (mm): 12 x 12 x 1.7
Lead pitch (mm): 0.8
MSL: 3
Reflow max (°C): 260

Package: 196 caBGA
Total Device Weight: 0.366 Grams

Package Code:

BG196

Products:

LFD2-NX

September, 2021

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	3.07%	0.0113	3.07%	0.0113	Silicon chip	7440-21-3	100.00%	Die size: 4.69 x 5.07mm
Mold Compound	51.44%	0.1884	45.01%	0.1648	Silica	60676-86-0	87.50%	Mold Compound: KE-G1250AAS
			3.34%	0.0122	Epoxy resin	-	6.50%	
			2.83%	0.0104	Phenol Resin	-	5.50%	
			0.26%	0.0009	Carbon Black	1333-86-4	0.50%	
D/A Epoxy	1.11%	0.0041	0.89%	0.00324	Silver	7440-22-4	80.00%	Die attach epoxy: Henkel (Ablebond) 2100A
			0.22%	0.00081	Esters & resins	-	20.00%	
Wire	0.56%	0.0020	0.54%	0.00198	Copper	7440-50-8	96.55%	0.8 mil diameter; 1 wire per solder ball
			0.02%	0.00006	Palladium	7440-05-3	3.10%	
			0.00%	0.00001	Gold	7440-57-5	0.34%	
Solder Balls	20.53%	0.0752	19.81%	0.0725	Tin (Sn)	7440-31-5	96.50%	SAC305
			0.62%	0.0023	Silver (Ag)	7440-22-4	3.00%	
			0.10%	0.0004	Copper (Cu)	7440-50-8	0.50%	
Substrate	6.52%	0.0239	2.09%	0.0076	BT Resins	-	32.00%	BT Resin CCL-HL832NX-A
			4.43%	0.0162	Glass fiber	65997-17-3	68.00%	
Foil	11.65%	0.0426	11.65%	0.0426	Copper	7440-50-8	100.00%	
Solder Mask	5.12%	0.0187	2.88%	0.0105	Quartz	14808-60-7	56.20%	Solder mask PSR4000 AUS 308
			0.82%	0.0030	3-methoxy-3-methylbutylacetate	103429-90-9	16.00%	
			1.13%	0.0041	Barium Sulfate	7727-43-7	22.00%	
			0.15%	0.0006	Talc (containing no asbestiform fibers)	14807-96-6	3.00%	
			0.03%	0.0001	Naphthalene	91-20-3	0.50%	
			0.12%	0.0004	Trade secret ingredients	-	2.30%	

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Rev. B